

B.O.M. List for VC7584_A6_01_FFCFC
(Assembly)

发行部门: 封装工程 发行人: XXX 版本: AB-OI-A0 生效日期: 2014-04-23

Stage	S/N	品名	Item	Material Specification	Vendor P/N	XX P/N	Qty	Unit	Vendor	Bar-code
Dicing	1	Dicing Blade								
	2	Mounting Tape								
SMT	3	Substrate	6 * 6	VC7590_14_L2_E					旭德	
	4	Solder Paste		90% Sn / 10% Sb						
	5	Cleaning Solvent								
	6	Passive component	C1	CAP 0201 X7R 25V 330pF 10%						
	7	Passive component	C3	CAP 0201 C0G 25V 33pF 5%						
	8	Passive component	C2	CAP 0201 C0G 25V 22pF 5%						
	9	Passive component		CAP 0201 C0G 25V 15pF 2%						
	10	Passive component		CAP 01005 X7R 10V 330pF ±10%						
	11	Passive component		CAP 01005 C0G 16V 68pF ±5%						
	12	Passive component		CAP 0201 X5R 10V 10000pF 10%						
	13	Passive component		CAP Hi-Q 0201 C0G 6.3V 27pF 5%						
	14	Passive component		CAP 0201 C0G 25V 12pF 5%						
	15	Passive component		CAP 0201 C0G 25V 9.1pF +0.1pF						
	16	Passive component		CAP 0201 C0G 25V 3.5pF +0.1pF						
	17	Passive component		CAP 0201 C0G 25V 5.0pF +0.1pF						
	18	Passive component		CAP 0201 C0G 25V 1.8pF +0.1pF						
	19	Passive component		CAP 0201 C0G 25V 8.0pF +0.25pF						
	20	Passive component		IND, 0201, 1.2nH±0.1nH						
	21	Passive component		IND 0201 15 nH 3%						
	22	Passive component		IND 0201 3.6nH +0.1 nH						
Die Attach	23	銀膠 Epoxy		Ablebond84-1 LMISR4 5CC Ablebond84-1 LMISR4 2.5CC						
	24	AH825A-R0	U1	0.855mmx1.073mm x 0.100mm						
	25	00CX281	U2	0.830mmx1.120mm x 0.250mm						
	26	TMET74J	U3	1.145mmx0.890mm x 0.250mm						
	27	Collet								
Wire Bonding	28	Substrate								
	29	Bond Wire		1.0mil / Au ≥99.99%						
Mold	30	Capillary								
	31	Mold Compound		G760T 14*7.0g						
	32	Waxing Rubber								
Singulation	33	Cleaning Rubber								
	34	Saw Blade								